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(sample or sampling) and process and wafer
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» Key

IEEE JNL	IEEE Journal or Magazine
IEE JNL	IEE Journal or Magazine
IEEE CNF	IEEE Conference Proceeding
IEE CNF	IEE Conference Proceeding
IEEE STD	IEEE Standard

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☐   1. **A cost-based heuristic for statistically determining sampling frequency ir**
Chen-Fu Chien; Shao-Chung Hsu; Peng, S.; Chia-Hung Wu;
Semiconductor Manufacturing Technology Workshop, 2000
14-15 June 2000 Page(s):217 - 229
Digital Object Identifier 10.1109/SMTW.2000.883099

AbstractPlus | Full Text: PDF(556 KB)   IEEE CNF

☐   2. **Defect inspection sampling plans-which one is right for me?**
Scanlan, B.;
Advanced Semiconductor Manufacturing Conference and Workshop, 1998. 19
23-25 Sept. 1998 Page(s):103 - 108
Digital Object Identifier 10.1109/ASMC.1998.731415

AbstractPlus | Full Text: PDF(660 KB)   IEEE CNF

☐   3. **Development of cost effective sampling strategy for in-line monitoring**
Tomlinson, W.; Nurani, R.K.; Burns, M.; Shanthikumar, J.G.;
Advanced Semiconductor Manufacturing Conference and Workshop, 1997. IEl
10-12 Sept. 1997 Page(s):8 - 12
Digital Object Identifier 10.1109/ASMC.1997.630696

AbstractPlus | Full Text: PDF(468 KB)   IEEE CNF

☐   4. **A methodology for determining capacity consumption due to the samplir**
the photolithography metrology sector in a multi-part number, multi-techı
fabricator
Butler, K.L.; Woods, R.;
Advanced Semiconductor Manufacturing Conference and Workshop, 1999 IEE
8-10 Sept. 1999 Page(s):113 - 116
Digital Object Identifier 10.1109/ASMC.1999.798195

AbstractPlus | Full Text: PDF(396 KB)   IEEE CNF

☐   5. **Key considerations in the development of defect sampling methodologie:**
McIntyre, M.; Nurani, R.K.; Akella, R.;
Advanced Semiconductor Manufacturing Conference and Workshop, 1996. AS
Proceedings. IEEE/SEMI 1996
12-14 Nov. 1996 Page(s):81 - 85
Digital Object Identifier 10.1109/ASMC.1996.557977

AbstractPlus | Full Text: PDF(484 KB)   IEEE CNF

6. **Defect sampling methodology: the development of an effective defect sai during the initial start-up phase of a 0.35 /spl mu/m fabrication facility**
Cappel, R.; Hilton, R.; Lim, J.;
Advanced Semiconductor Manufacturing Conference and Workshop, 1995. AS Proceedings. IEEE/SEMI 1995
13-15 Nov. 1995 Page(s):271
Digital Object Identifier 10.1109/ASMC.1995.484384

AbstractPlus | Full Text: PDF(36 KB)   IEEE CNF

7. **Process control and base line monitoring using optical 'On the Fly' and S classification as implemented in advanced DRAM manufacturing**
Ralf, S.; Sina, P.; Dvori, S.; Bernhard, M.;
Advanced Semiconductor Manufacturing Conference and Workshop, 2003 IEE
31 March-1 April 2003 Page(s):67 - 72

AbstractPlus | Full Text: PDF(498 KB)   IEEE CNF

8. **Role of in-line defect sampling methodology in yield management**
Nurani, R.K.; Akella, R.; Strojwas, A.J.; Wallace, R.;
Semiconductor Manufacturing, 1995., IEEE/UCS/SEMI International Symposiu
17-19 Sept. 1995 Page(s):243 - 247
Digital Object Identifier 10.1109/ISSM.1995.524400

AbstractPlus | Full Text: PDF(460 KB)   IEEE CNF

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Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	103	702/83.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 15:45
L2	1	702/83.ccls. and (metrology with sampl$3 with rule)	US-PGPUB	OR	ON	2005/09/01 15:46

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	103	702/83.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 09:07
L9	5	L1 and (sampl$3 with (significance magnitude substance value weight$3)) and (active initiat$3 trigger$3) and sampl$3 and process and sampling and (rule plan condition parameter) and (work$piece (work adj piece) lot wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 09:38
L10	13	purdy-matthew-$.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 09:39
L11	17910	advanced adj micro adj devices$.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 09:39
L12	17	(L10 L11) and (sampl$3 with (significance magnitude substance value weight$3)) and (active initiat$3 trigger$3) and sampl$3 and process and sampling and (rule plan condition parameter) and (work$piece (work adj piece) lot wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 10:36
L13	2231	700/96,121,108-110.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 10:36
L14	35	L13 and (sampl$3 with (significance magnitude substance value weight$3)) and (active initiat$3 trigger$3) and sampl$3 and process and sampling and (rule plan condition parameter) and (work$piece (work adj piece) lot wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 10:42

L17	4	L13 and (sampl$3 with (significance magnitude substance value weight$3)) and (active initiat$3 trigger$3) and sampl$3 and process and sampling and (rule plan condition parameter) and (work$piece (work adj piece) lot wafer) and ((cumulati$3 collect$3 increas$3 grow$3 combin$3 summati$3 summ$3 total combination) same (sample sampling) same (value weight$3) same (active initiat$3 trigger$3))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 10:43
L18	4785	((702/81,83,84,182-185) or (700/90,108-111)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/01 10:42
L19	7398	((702/81,83,84,182) or (700/95, 108-110,116,117,121) or (438/5,7, 8,14)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/09/01 10:42
L20	97	(L18 L19) and (sampl$3 with (significance magnitude substance value weight$3)) and (active initiat$3 trigger$3) and sampl$3 and process and sampling and (rule plan condition parameter) and (work$piece (work adj piece) lot wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 10:47
L22	49	("6392229" "4864522" "4969191" "6766214" "6821792" "6424876" "6780552" "5712707" "5757507" "5621514" "4798469" "4804924" "4857836" "5206820" "5563709" "5576948" "5739524" "5778016" "5789124" "5900624" "5940194" "6023338" "6072899" "6079256" "6100978" "6166801" "6225639" "6225639" "6233056" "6236344" "6246044" "6266581" "6396856" "6427345" "6442496" "6494766" "6524165" "6650955" "6754593" "6764380" "6833221" "6842251" "6859746" "6891626" "6897665" "6899982" "6922600" "5442166" "5731877" "6226074").pn.	US-PGPUB; USPAT	OR	ON	2005/09/01 10:46

L23	5	(L22) and (sampl$3 with (significance magnitude substance value weight$3)) and (active initiat$3 trigger$3) and sampl$3 and process and sampling and (rule plan condition parameter) and (work$piece (work adj piece) lot wafer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 10:47
L24	5	("5150289" | "5465221" | "5497331" | "5761064" | "5862054").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/09/01 10:50
L25	8	("6477432").URPN.	USPAT	OR	ON	2005/09/01 10:51

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	1	10/634013	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 13:36
S2	13	purdy-matthew-$.in.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 18:54
S3	17866	advanced adj micro adj devices$.as.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 18:54
S4	2	(S2 S3) and metrology and weight and trigger	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 18:57
S6	101	702/83.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 18:56
S7	1	S6 and metrology and weight and trigger	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/09/01 09:07
S9	117	metrology and weight and trigger not S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 19:05
S11	73	metrology and weight and trigger and semiconduct$3 not S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 19:05
S12	35	metrology and weight and trigger and semiconduct$3 and value and rule not S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 19:06
S13	3	metrology and weight and trigger and semiconduct$3 and value and rule and lot not S3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/22 19:09

S14	2	(("5541846") or ("6442496")).PN.	US-PGPUB; USPAT	OR	OFF	2005/08/22 19:09
S16	48	(("6392229") or ("4864522") or ("4969191") or ("6766214") or ("6821792") or ("6424876") or ("6780552") or ("5712707") or ("5757507") or ("5621514") or ("4798469") or ("4804924") or ("4857836") or ("5206820") or ("5563709") or ("5576948") or ("5739524") or ("5778016") or ("5789124") or ("5900624") or ("5940194") or ("6023338") or ("6072899") or ("6079256") or ("6100978") or ("6166801") or ("6225639") or ("6225639") or ("6233056") or ("6236344") or ("6246044") or ("6266581") or ("6396856") or ("6427345") or ("6442496") or ("6494766") or ("6524165") or ("6650955") or ("6754593") or ("6764380") or ("6833221") or ("6842251") or ("6859746") or ("6891626") or ("6897665") or ("6899982") or ("6922600") or ("5442166") or ("5731877") or ("6226074).pn.")).PN.	US-PGPUB; USPAT	OR	OFF	2005/08/25 08:16
S17	45	S16 and metrology and sampl$3	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 08:45
S18	6	S16 and metrology and sampl$3 and weight	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 09:03
S21	3	"6708129".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 08:58
S22	4770	((702/81,83,84,182-185) or (700/90,108-111)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/25 08:58
S25	7369	((702/81,83,84,182) or (700/95, 108-110,116,117,121) or (438/5,7, 8,14)).CCLS.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/08/25 09:00

S29	36	(S22 S25) and metrology and sampl$3 and weight	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 09:03
S30	22	(S22 S25) and metrology and sampl$3 and weight and process and controller	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 09:03
S31	8	(S22 S25) and metrology and sampl$3 and weight and process and controller and dynamic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 09:05
S33	2	(S22 S25) and (metrology with sampl$3) and weight and process and controller and dynamic	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 10:20
S34	2	"6477432".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 10:31
S35	5	("5150289" | "5465221" | "5497331" | "5761064" | "5862054").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/25 10:23
S36	8	("6477432").URPN.	USPAT	OR	ON	2005/08/25 10:26
S37	3	"6442496".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/25 10:31
S38	3	("6245581" | "6248602" | "6337217").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/25 10:32
S39	8	("6442496").URPN.	USPAT	OR	ON	2005/08/25 10:34
S40	1	"6859746".pn.	USPAT	OR	ON	2005/08/25 10:34
S41	27	("20020135781" | "20030204348" | "20040121495" | "5867276" | "5877860" | "5880838" | "5956692" | "6051348" | "6055463" | "6081334" | "6115643" | "6141107" | "6223098" | "6245584" | "6319884" | "6383888" | "6423977" | "6433878" | "6445969" | "6479200" | "6529282" | "6597447" | "6643557" | "6650955" | "6721939" | "6742168" | "6766214").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2005/08/25 10:34

S42	1	(metrology with sampl$3 with rule) and (workpiece lot) and wafer and ((trigger active stimulus threshold) with value)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 13:40
S44	27	(metrology with sampl$3) and (workpiece lot) and wafer and ((trigger active stimulus threshold activate actuate) with value)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 13:41
S45	27	(metrology with sampl$3) and (workpiece lot) and wafer and ((trigger active stimulus threshold activate actuate) with value) and process	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 13:41
S47	27	(metrology with sampl$3) and (workpiece lot) and wafer and ((trigger active stimulus threshold activate actuate) with value) and process and (micro$processor (micro adj processor) controller computer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON ·	2005/08/30 13:42
S48	27	(metrology with sampl$3) and (workpiece lot) and wafer and ((trigger active stimulus threshold activate actuate) with value) and process and (micro$processor (micro adj processor) controller computer) and tool	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 13:43
S49	5	(metrology with sampl$3) and (workpiece lot) and wafer and ((trigger active stimulus threshold activate actuate) with value) and process and (micro$processor (micro adj processor) controller computer) and tool and rule	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:19
S51	16	S49 "6871114".pn. "6477432".pn. "6442496".pn. "6859746".pn. "6650955".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 14:22
S52	11	(S49 "6871114".pn. "6477432".pn. "6442496".pn. "6859746".pn. "6650955".pn. "6687561".pn.) and (metrology with sampl$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 14:30
S53	1	(S49 "6871114".pn. "6477432".pn. "6442496".pn. "6859746".pn. "6650955".pn. "6687561".pn.) and (metrology with sampl$3) and (workpiece lot) and (sampl$3 with rule)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 14:36

S54	5	(S49 "6871114".pn. "6477432".pn. "6442496".pn. "6859746".pn. "6650955".pn. "6687561".pn.) and (metrology with sampl$3) and (workpiece lot) and rule	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 14:33
S55	3	(S49 "6871114".pn. "6477432".pn. "6442496".pn. "6859746".pn. "6650955".pn. "6687561".pn.) and (metrology with sampl$3) and (workpiece lot) and (sampl$3 with (condition rule ruling))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 14:38
S56	5	(S49 "6871114".pn. "6477432".pn. "6442496".pn. "6859746".pn. "6650955".pn. "6687561".pn.) and (metrology with sampl$3) and (workpiece lot) and (sampl$3 with (plan condition rule ruling))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/30 16:29
S57	2	"6650955".pn. and (metrology same sampling same plan)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:26
S59	3	(metrology same sampl$3 same plan) and (workpiece lot) and wafer and ((trigger active stimulus threshold activate actuate) with value) and process and (micro$processor (micro adj processor) controller computer) and tool	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:19
S60	1166	sampling with weight$3 with value	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 08:26
S61	5	(sampling with weight$3 with value) and metrology	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 13:50
S62	2	"6477432".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 14:10
S63	2	"6477432".pn. and (lot same rule same sampl$3)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 15:26

S64	491	(semiconduct$3 same wafer) and process and ((cumulati$3 collect$3 increas$3 grow$3 combin$3 summati$3 summ$3 total combination) same sampl$3 same (trigger$4 threshold$3 value) same (weight condition rule))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 15:37
S65	35	(semiconduct$3 same wafer) and process and ((cumulati$3 collect$3 increas$3 grow$3 combin$3 summati$3 summ$3 total combination) same sampl$3 same (trigger$4 threshold$3 value) same (weight condition rule)) and metrology	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 15:40
S66	18	(semiconduct$3 same wafer) and process and ((cumulati$3 collect$3 increas$3 grow$3 combin$3 summati$3 summ$3 total combination) same sampl$3 same (trigger$4 threshold$3 value) same (weight condition rule)) and metrology and defect	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 15:41
S67	8	(semiconduct$3 same wafer) and process and ((cumulati$3 collect$3 increas$3 grow$3 combin$3 summati$3 summ$3 total combination) same sampl$3 same (trigger$4 threshold$3 value) same (weight condition rule)) and metrology and defect and inspection	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 15:41
S68	3	(semiconduct$3 same wafer) and process and ((cumulati$3 collect$3 increas$3 grow$3 combin$3 summati$3 summ$3 total combination) same sampl$3 same (trigger$4 threshold$3 value) same (weight condition rule)) and metrology and defect and inspection and lot	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 15:47
.S70	41	(semiconduct$3 same wafer) and process and ((cumulati$3 collect$3 increas$3 grow$3 combin$3 summati$3 summ$3 total combination) same sampl$3 same (trigger$4 threshold$3 value) same (weight condition rule))and defect and inspection and lot	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/08/31 15:48

| S72 | 141 | ((cumulati$3 collect$3 increas$3 grow$3 combin$3 summati$3 summ$3 total combination) same (sample sampling) same (weight condition rule) same (trigger$4 threshold$3 value)) and lot and wafer and semiconduct$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/31 15:51 |
| S73 | 7 | ((cumulati$3 collect$3 increas$3 grow$3 combin$3 summati$3 summ$3 total combination) with (sample sampling) with (weight condition rule) with (trigger$4 threshold$3 value)) and lot and wafer and semiconduct$4 | US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB | OR | ON | 2005/08/31 15:51 |